Attorney Docket No.: 111079-135918

IPN P14927X (Intel Corporation)

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Boggs, et al.

Application No.: 10/750,56

Filed: December 31, 2003

For: Electronic Substrate with Direct

**Inner Layer Component** 

Interconnection

Mail Stop RCE Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450 Examiner: Ishwarbhai B. Patel

Art Unit: 2841

Confirmation No. 5692

## **CERTIFICATE OF TRANSMISSION/MAILING**

I hereby certify that this correspondence is being facsimile transmitted to the USPTO or deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on the date shown below:

Typed or Printed: Heathen L., Adamson

Signature: Date: 11/02/2005

## AMENDMENT AND RESPONSE ACCOMPANYING RCE

Dear Sir:

Due to the nonentry of the previously proposed amendments as relayed by the Advisory Action mailed October 25, 2005, Applicants resubmit the following response to the Final Office Action mailed August 8, 2005, accompanied by a request for continued examination:

Amendments to the Specification - none;

Amendments to the Claims – are reflected in the listing of claims that begin on page 2 of this paper;

Amendments to the Drawings - none; and

Remarks/Arguments – begin on page 6 of this paper.